

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

GBL8005-MS THRU GBL810-MS

Product specification

REVERSE VOLTAGE - 50 to 1000 Volts
FORWARD CURRENT - 8.0 Amperes


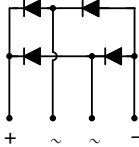
FEATURES

- deal for printed circuit board mounting
- The plastic material used carries Underwriters Laboratory flammability recognition 94V-0
- Built-in printed circuit board stand-offs
- High case dielectric strength
- High temperature soldering guaranteed
260 /5 seconds at 5 lbs (2.3kg) tension





MECHANICAL DATA

- Case: Reliable low cost construction utilizing
- molded plastic technique
- Terminals: Plated leads solderable per
MIL-STD-202,Method 208
- Mounting Position: Any

REFERENCE NEWS

GBL



Marking

GBL8005-MS	GBL801-MS	GBL802-MS	GBL804-MS
			
GBL806-MS	GBL808-MS	GBL810-MS	
			

MAXIMUM RATINGS & THERMAL CHARACTERISTICS

Rating at 25 °C ambient temperature unless otherwise specified, Resistive or Inductive load, 60 Hz.
For Capacitive load derate current by 20%.

Parameter	Symbol	GBL8005-MS	GBL801-MS	GBL802-MS	GBL804-MS	GBL806-MS	GBL808-MS	GBL810-MS	unit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS bridge input voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified output current at $T_C=100^{\circ}C$ (with heatsink)	$I_{F(AV)}$	8.0							A
Peak forward surge current single sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	175							A
Rating for fusing ($t<8.3ms$)	I^2t	127							A^2sec
Operating junction and storage temperature range	T_J, T_{STG}	-55 to + 150							$^{\circ}C$

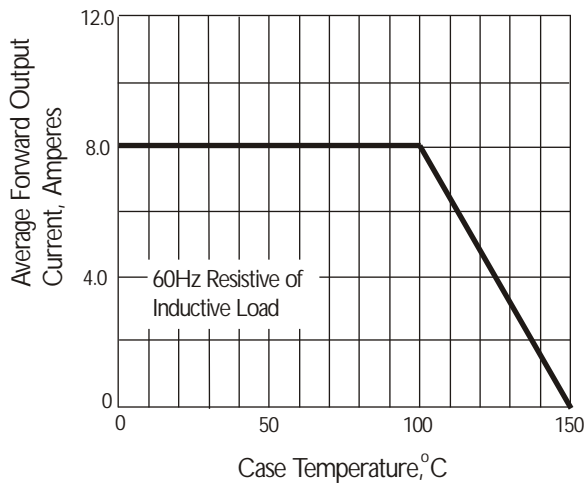
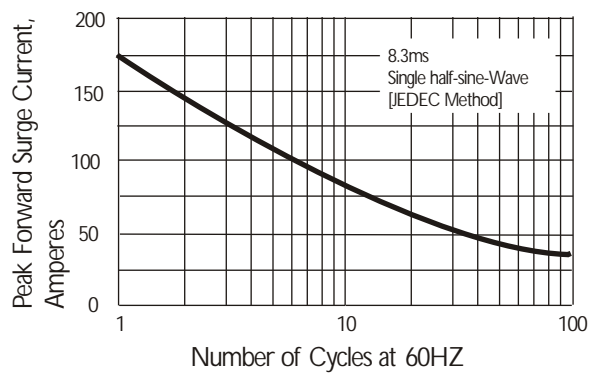
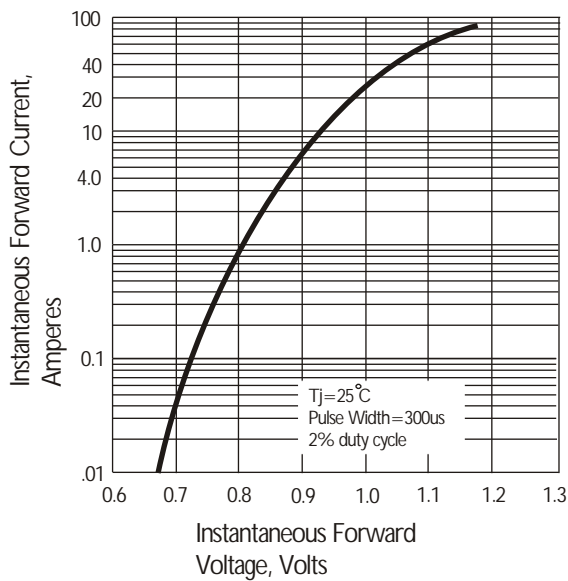
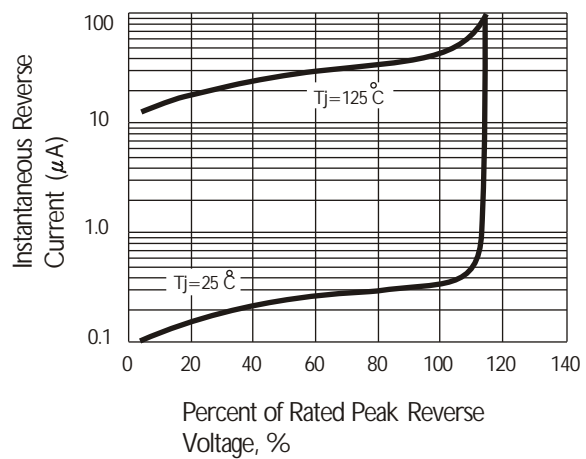
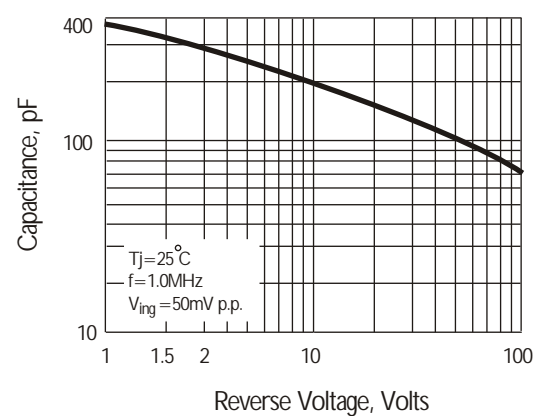
Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified. Resistive or Inductive load, 60Hz.
For Capacitive load derate by 20 %.

Parameter	Symbol	GBL8005-MS	GBL801-MS	GBL802-MS	GBL804-MS	GBL806-MS	GBL808-MS	GBL810-MS	Unit
Maximum instantaneous forward voltage drop per leg at 4.0A	V_F	1.1							V
Maximum DC reverse current at rated $T_A=25^{\circ}C$ DC blocking voltage per element $T_A=125^{\circ}C$	I_R	10 500							μA

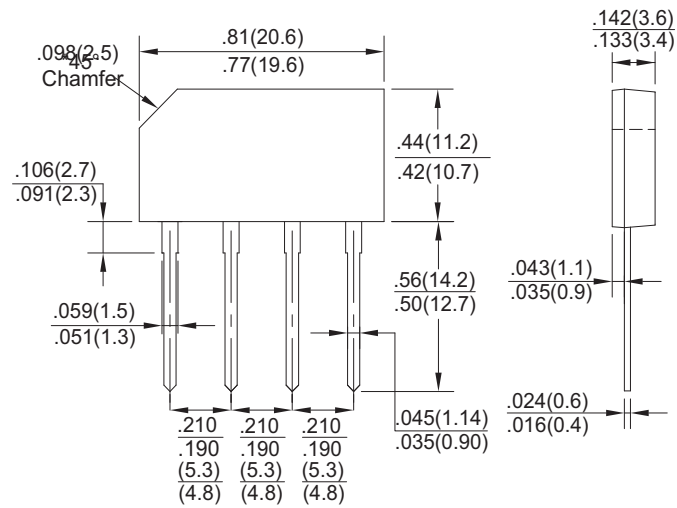
Notes: (1)Thermal resistance from Junction to Ambient on P.C.board mounting.

Rating and Characteristic Curves ($T_A = 25^{\circ}\text{C}$ Unless otherwise noted)

Fig. 1 Derating Curve for Output Rectified Current

Fig. 2 Maximum Non-repetitive Peak Forward Surge Current

Fig. 3 Typical Instantaneous Forward Characteristics

Fig. 4 Typical Reverse Characteristics

Fig. 5 Typical Junction Capacitance


PACKAGE MECHANICAL DATA

GBL



Dimensions in inches and (millimeters)

REEL SPECIFICATION

P/N	PKG	QTY
GBL8005-MS THRU GBL810-MS	GBL	500

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